· · · · · · · · · · · · · · · · · · ·	04-03-2002 U.S. DEPARTMENT OF COMM 102040807 Patent and Trademark Office
To the Honorable Commissioner of Patents and Trademarks: Pleas	e record the attached original documents or copy thereof.
<ol> <li>Name of conveying party(ies)</li> <li>Makoto SUDO</li> <li>Daisuke WATARI</li> <li>Kazuhiko WATANABE</li> <li>Additional name(s) of conveying party(ies) attached No</li> </ol>	<ul> <li>2. Name and address of receiving party(ies)</li> <li>Name: Fujikoki Corporation</li> <li>Internal Address:</li> </ul>
3. Nature of conveyance:	Street Address: 17-24, Todoroki 7-chome, Setagaya-ku
X Assignment	City: Tokyo, Japan
□ Security Agreement □ Change of Name	Additional name(s) & address(es) attached  Yes  No
Other Execution Date: February 28, 2002 4. Application number(s) or patent number(s): 10/051,181	
If the document is being filed together with a new application, the Additional f	ne execution date of the application is
<ol> <li>Name and address of party to whom correspondence concerning document should be mailed:</li> </ol>	6. Total number of applications and patents involved: 1
Name: RADER, FISHMAN & GRAUER	7. Total fee (37 CFR 3.41)\$ <b>40.00</b>
Internal Address: Suite 501	□ Enclosed
	Authorized to be charged to Deposit Account
Street Address: 1233 20 <sup>th</sup> Street, NW	8. Deposit account number: 18-0013
City: Washington, D.C. Zip: 20036	(Attach duplicate copy of this page if paying by deposit account
City: Washington, D.C. Zip: 20036	(Attach duplicate copy of this page if paying by deposit account

REEL: 012728 FRAME: 0976

Docket Number:

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

## Thermal Expansion Valve

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, FUJIKOKI CORPORATION , a Japanese corporation with offices at 17-24, Todoroki 7-chome, Setagaya-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of Ten Dollar (\$10.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-totime present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 10/051,181 \_\_\_\_\_\_, Filing Date: January 22, 2002 \_\_\_\_.

This assignment executed on the dates indicated below.

Makoto SUDO	
Name of first inventor c/o FUJIKOKI CORPORATION	Execution date of U.S. Patent Application
17-24, Todoroki 7-chome, Setagaya	-ku, Tokyo, Japan
Residence of first inventor	
makata Suda	28 Feb 2002
Signature of first inventor	Date of this assignment
Daisuke WATARI	
Name of second inventor	Execution date of U.S. Patent Application
c/o FUJIKOKI CORPORATION	- -
17-24, Todoroki 7-chome, Setagaya	a-ku, Tokyo, Japan
Residence of second inventor	
Datsuke Watari	28 Feb 2002
Datsike Watari Signature of second inventor	28 Feb 2002 Date of this assignment
	Date of this assignment
Signature of second inventor	
Signature of second inventor Kazuhiko WATANABE	Date of this assignment
Signature of second inventor Kazuhiko WATANABE Name of third inventor c/o FUJIKOKI CORPORATION	Date of this assignment Execution date of U.S. Patent Application
Signature of second inventor Kazuhiko WATANABE Name of third inventor	Date of this assignment Execution date of U.S. Patent Application
Signature of second inventor <u>Kazuhiko WATANABE</u> Name of third inventor c/o FUJIKOKI CORPORATION <u>17-24, Todoroki 7-chome, Setagaya</u> Residence of third inventor	Date of this assignment Execution date of U.S. Patent Application Ba-ku, Tokyo, Japan 28 Feb 2002
Signature of second inventor Kazuhiko WATANABE Name of third inventor c/o FUJIKOKI CORPORATION	Date of this assignment Execution date of U.S. Patent Application

------

PATENT REEL: 012728 FRAME: 0978 Name of fourth inventorExecution date of U.S. Patent ApplicationResidence of fourth inventorDate of this assignmentSignature of fourth inventorDate of U.S. Patent ApplicationName of fifth inventorExecution date of U.S. Patent ApplicationResidence of fifth inventorDate of this assignmentSignature of fifth inventorDate of this assignmentName of sixth inventorExecution date of U.S. Patent ApplicationResidence of sixth inventorDate of this assignmentSignature of sixth inventorDate of U.S. Patent ApplicationResidence of sixth inventorDate of U.S. Patent Application

PATENT REEL: 012728 FRAME: 0979

**RECORDED: 03/26/2002**